

Rostec State Corporation launched serial production of special adhesive compounds for the electronic industry. The development of Rosel holding is designed to replace imported analogues previously used in the production of secure electronics.

The new glue has high electrical conductivity and thermal conductivity (up to 10.5 W/m*K), which is comparable to metals. The material retains properties in a wide temperature range - from -60°C to $+175^{\circ}\text{C}$. The density of the composition is at least 3.6 g/cm^3 , which provides a reliable connection without the formation of voids.

The development of the Central Design Bureau of Special Radio Materials (Central Design Bureau of the Republic of Moldova) is used in the creation of micro -gaps for secure laptops, radars and control systems. Unlike soldering, glue does not require high temperatures for curing, which eliminates the deformation of sensitive components.

According to the company, the material does not contain solvents and will reduce the cost of production. The product has already passed tests and is protected by a patent.